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DP-305004, Page 1

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Assistant Commissioner for Patents
Box Patent Application
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No.: DP-305004

Inventors : MIKEL R. FULK
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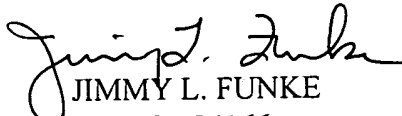
Title : HIGH DENSITY WIRE BONDABLE CONNECTOR ASSEMBLY

Filing Fee Formula

Basic Fee.....	\$	740.00
Additional Fees:		
Number of independent claims in excess of 3, times \$80.00	\$	0.00
Number of claims in excess of 20, times \$18.00	\$	0.00
Multiple dependent claim, add \$270.00	\$	0.00
Total Filing Fee.....	\$	740.00

The patent specification DP-305004 entitled HIGH DENSITY WIRE BONDABLE CONNECTOR ASSEMBLY and filed in the Patent and Trademark Office herewith is the patent specification for which the inventor(s) executed the Declaration enclosed herewith.

Please charge the \$ 740.00 filing fee to DELPHI TECHNOLOGIES INC. Deposit Account No. 50-0831.


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Enclosures

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